

**PATENT APPLICATION TRANSMITTAL LETTER**  
(Large Entity)

Docket No.  
MICT-0050-US (99-0325)

TO THE ASSISTANT COMMISSIONER FOR PATENTS

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

**D. Rumsey**

For: Positioning Flowable Solder for Bonding Integrated Circuit Elements

Enclosed are:

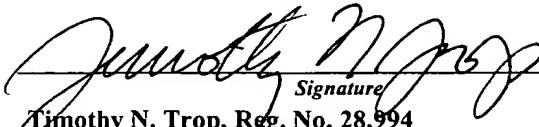
- Certificate of Mailing with Express Mail Mailing Label No. EL360180020US  
 2 sheets of drawings.  
 A certified copy of a application.  
 Declaration  Signed.  Unsigned.  
 Power of Attorney  
 Information Disclosure Statement  
 Preliminary Amendment  
 Other: Recordation Form Cover Sheet and Assignment

**CLAIMS AS FILED**

For	#Filed	#Allowed	#Extra	Rate	Fee
Total Claims	30	- 20 =	10	x \$18.00	\$180.00
Indep. Claims	4	- 3 =	1	x \$78.00	\$78.00
Multiple Dependent Claims (check if applicable)	<input type="checkbox"/>				\$0.00
				BASIC FEE	\$760.00
				TOTAL FILING FEE	\$1,018.00

- A check in the amount of \$1,018.00 to cover the filing fee is enclosed.  
 The Commissioner is hereby authorized to charge and credit Deposit Account No. 20-1504 as described below. A duplicate copy of this sheet is enclosed.
- Charge the amount of as filing fee.  
 Credit any overpayment.  
 Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.  
 Charge the issue fee set in 37 C.F.R. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

Dated: 8/18/99

  
Signature  
Timothy N. Trop, Reg. No. 28,994

Trop, Pruner, Hu & Miles, P.C.  
8554 Katy Freeway, Suite 100  
Houston, TX 77024  
(713) 468-8880 [Ph]  
(713) 468-8883 [Fax]

cc: